电性参数

Ta=25 Absolute Maximum Rating(ta=25)

Power Dissipation	500	mW
Forward current	40	mA
Peak Forward Current	100	mA
Electrostatic Discharge	3000	V
Operation Temperature Range	-40 to +60	
Storage Temperature Range	-40 to +85	
Lead Soldering Temperature	260 ≤6S	

* ≤0.1ms ≤1/10 * Note: Pulse width ≤0.1ms, Duty ≤1/10

光电参数 Ta=25 Optical-electrical parameter(ta=25)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Peak wavelength	λp	IF=100mA	260	270	280	nm
Radiation Flux	Φe		10	-	15	mw
Forward voltage	VF		5.0	-	6.5	V
Half light angle	2θ1/2		-	120	-	Deg
Half wave width	HW		-	15	-	nm
Reverse current	IR	VR=5V	-	-	5	μA

辐射功率:

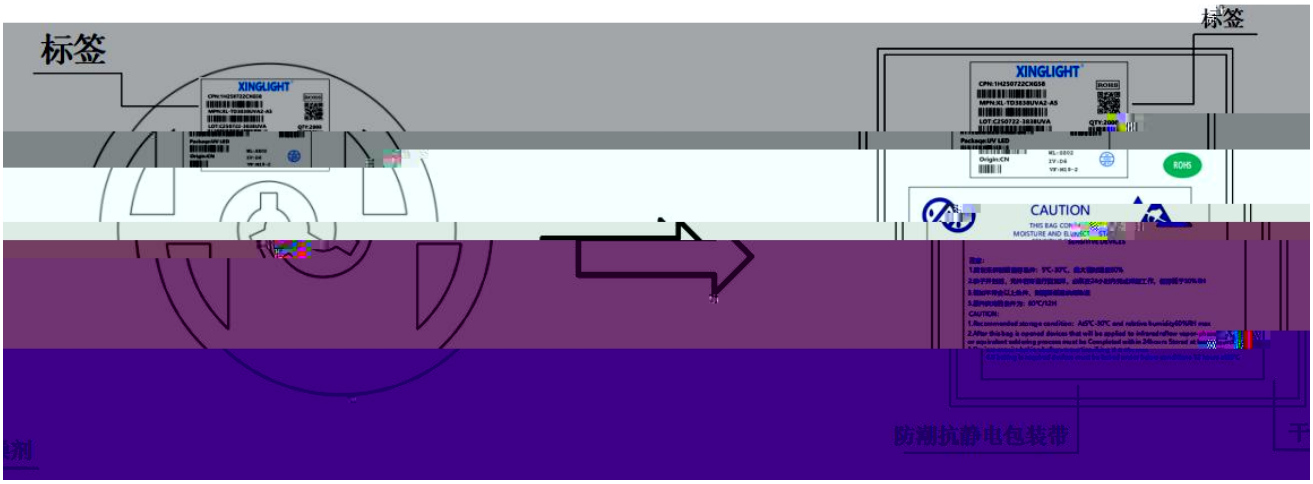
外形尺寸

Outline Dimension

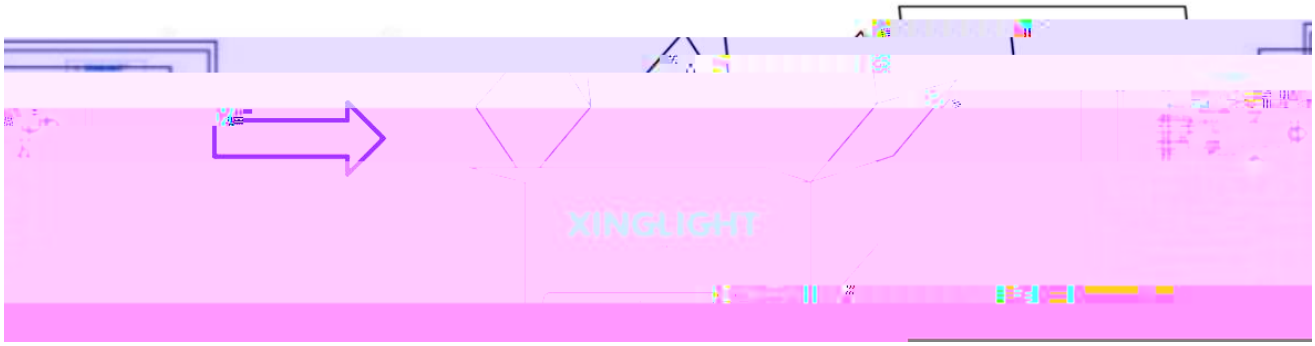
包装（2）

Packaging (2)

◇ 防潮抗静电包装 Moisture Proof and Antti-Electrostic Foil Bag



◇ 外包装箱 Cardboard Box



◇ 标签说明 Label Expantion：

CPN：批号/档位　　LOT：日期/封装颜色

MPN：型号　　VF：电压代码

WL：波长代码　　IV：亮度代码

ORIGIN：产地　　QTY：数量

PACKAQE：封装

焊接指导（2）

Guideline for Soldering (2)

清洗：

30 3 50

30

LED

300W LED

LED

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50 for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

* **注意：** PCB

PCB

* This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is influenced by many factors, it should be specialized base on the PCB designs and configurations of the soldering equipment..

XINGLIGHT®

Part No. :X